ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® Material Composition © Copyright 2005. IPC, Banı international and Pan-Americ	ockburn, Illinois, A	Il rights reserved un ntions.	nder both le	his docume evel parts, t	ent is a declarati he declaration e	on of the substan	ces within the manufactur ower level materials for w	rer listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on		
Supplier Information												
mpany name* Company unique ID				Unique ID Authority				Response Date*				
onsemi									2023-06-08			
Contact Name	Title - Contact]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	et-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr	Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
МС	AC100EP131FAG BBG ECL FLIP		LOP 4BIT		2023-06-08		TW2		75.1	mg	Each	
Manufacturing Proccess Information					·						·	
Terminal Plating / Grid Array Material	I Terminal Base Alloy		-STD-020 MSL F	Rating	Peak Process Body Tempe		ature Max Time at Peak	Temperatu	ire Numbe	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 2					260	С	30	second	ls 3			
Comments												
ATTENTION: MSL 2 Rated item requires Dry Pa	ick (after electrical	test)										
or more information regarding material composi	tion please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.33	mg	Supplier	Silicon (Si)	7440-21-3		0.33	mg
Die Attach 3.19	3.19	mg	Supplier	Silver (Ag)	7440-22-4		2.3925	mg
			Supplier	Epoxy resins	129915-35-1		0.7975	mg
Lead Frame 49.99	49.99	mg	Supplier	Silver (Ag)	7440-22-4		0.15	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.05	mg
			Supplier	Silicon (Si)	7440-21-3		0.3499	mg
				Nickel (Ni)	7440-02-0		1.4997	mg
			Supplier	Copper (Cu)	7440-50-8		47.9404	mg
Mold Compound-Black	114.24	mg		Epoxy Phenol Resin	proprietary data		11.9952	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		102.2448	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.65	mg	Supplier	Gold (Au)	7440-57-5		0.65	mg